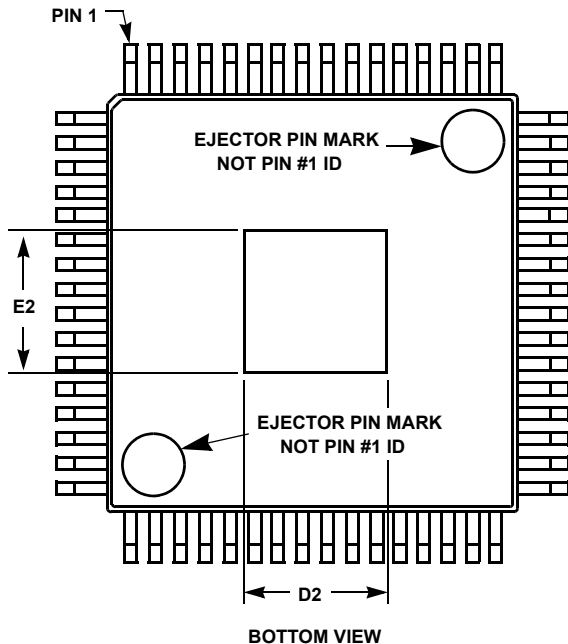
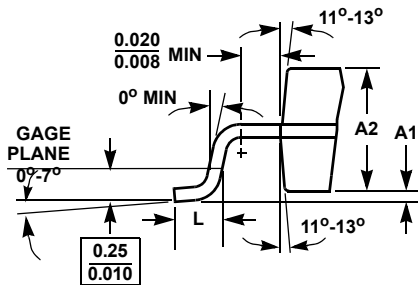
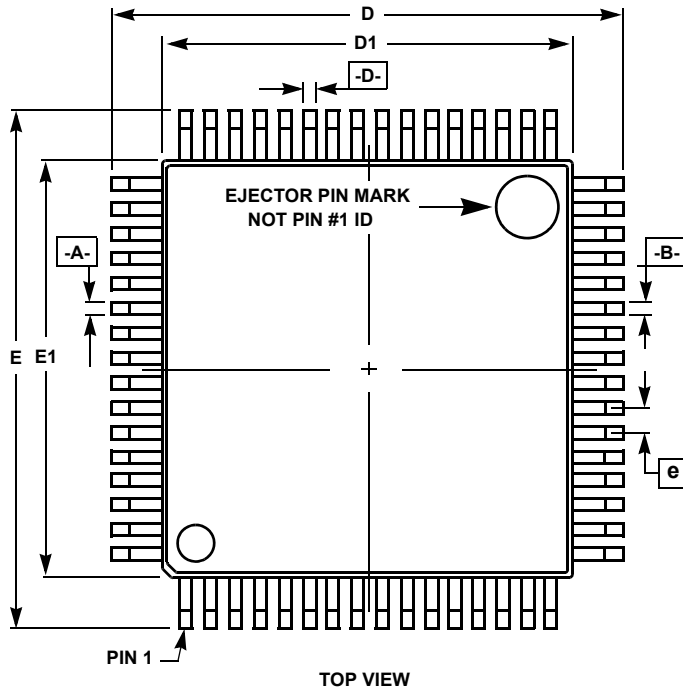


Plastic Packages for Integrated Circuits

Thin Plastic Quad Flatpack Exposed Pad Plastic Packages (EPTQFP)



Q64.10x10C (JEDEC MS-026ACD-HU ISSUE D)
64 LEAD THIN PLASTIC QUAD FLATPACK EXPOSED
PAD PACKAGE

SYMBOL	MILLIMETERS		NOTES
	MIN	MAX	
A	-	1.20	-
A1	0.05	0.15	-
A2	0.95	1.05	-
b	0.16	0.28	6
b1	0.17	0.23	-
D	11.80	12.20	3
D1	9.90	10.10	4, 5
D2	2.90	3.10	-
E	11.80	12.20	3
E1	9.90	10.10	4, 5
E2	2.90	3.10	-
L	0.45	0.75	-
N	64		7
e	0.50 BSC		-

Rev. 0 10/08

NOTES:

1. Controlling dimension: MILLIMETER. Converted inch dimensions are not necessarily exact.
2. All dimensions and tolerances per ANSI Y14.5M-1982.
3. Dimensions D and E to be determined at seating plane [-C-].
4. Dimensions D1 and E1 to be determined at datum plane [-H-].
5. Dimensions D1 and E1 do not include mold protrusion. Allowable protrusion is 0.25mm (0.010 inch) per side.
6. Dimension b does not include dambar protrusion. Allowable dambar protrusion shall not cause the lead width to exceed the maximum b dimension by more than 0.08mm (0.003 inch).
7. "N" is the number of terminal positions.

